# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

| HP Envy m6 Sleekbook |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1. Items listed below are classified as requiring selective treatment.
2. Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery and RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cords, Adapter</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 screw driver</td>
<td>Philip #1 / TORX T</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Log Low
2. Remove Battery Module
3. Remove RJ45 Door Assy
4. Remove IO Board Module
5. Remove Card Reader Board
6. Remove Fan Module
7. Remove thermal Module
8. Remove M/B Assy
9. Remove Display Assy
10. Remove K Lock Brk
11. Remove HDD Assy
12. Remove DC-IN Cable
13. Remove Log UP TP Assy
14. Remove Log UP Weight Assy
15. Remove Power PCB Module
16. Remove Speaker Assy FL
17. Remove Log Up Speaker R
18. Remove Log Up KB Sup Brk
19. Remove Log Up KB Module Assy
20. Remove TP Bridge Brk
21. Remove ESD Board
22. Divide Display Assy(Remove LCD Bezel)
23. Divide Display Assy(Remove LCD Panel )
24. Divide Display Assy(Remove LVDS Cable)
25. Divide Display Assy(Remove Hinge Brk L)
26. Divide Display Assy(Remove Hinge Brk R)
27. Divide Display Assy(Remove Antenna MIAN and AUX Cable)
28. Divide Display Assy(Remove Webcam Module)
29. Divide M/B Assy(Remove NGFF WLAN)
30. Divide M/B Assy(Remove RTC Battery)
31. Divide HDD Assy(Remove Hdd Cable)
32. Divide HDD Assy(Remove Hdd Brk Assy)
33. Divide Display assy (remove LCD cover AL skin)
34. Divide Log UP assy (remove Log up AL skin)
35. Divide Display Assy (Remove Touch Panel)
36. Divide Log UP TP Assy (Remove TP Brk)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove battery module
3.23 Remove service door
3.24 LCD module set disassembly
3.25 Top case disassembly
3.26 Thermal module and mother board disassembly
3.27 Bottom case disassembly
Step 1. Remove Log Low

Step 2. Remove Battery Module

Step 3. Remove RJ45 Door Assy

Step 4. Remove IO Board Assy
Step 5. Remove Card Reader Board

Step 6. Remove Fan Module

Step 7. Remove thermal Module

Step 8. Remove M/B Assy
Step 9. Remove Display Assy

Step 10. Remove K Lock Brk

Step 11. Remove HDD Assy

Step 12. Remove DC-IN Cable
Step 13. Remove Log UP TP Assy

Step 14. Remove Log UP Weight Assy

Step 15. Remove Power PCB Module

Step 16. Remove Speaker Assy FL

PSG instructions for this template are available at EL-MF877-01
Step 17. Remove Log Up Speaker R  
Step 18. Remove Log Up KB Sup Brk

Step 19. Remove Log Up KB Module Assy  
Step 20. Remove TP Bridge Brk
Step 21. Remove ESD Board

Step 22. Divide Display Assy (Remove LCD Bezel)

Step 23. Divide Display Assy (Remove LCD Panel)

Step 24. Divide Display Assy (Remove LVDS Cable)
Step 25. Divide Display Assy (Remove Hinge Brk L)  
Step 26. Divide Display Assy (Remove Hinge Brk R)  

Step 27. Divide Display Assy (Remove Antenna MIAN and AUX Cable)  
Step 28. Divide Display Assy (Remove Webcam Module)
Step29. Divide M/B Assy (Remove NGFF WLAN)  
Step30. Divide M/B Assy (Remove RTC Battery)  

Step31. Divide HDD Assy (Remove Hdd Cable)  
Step32. Divide HDD Assy (Remove Hdd Brk Assy)
Step 33. Divide Display assy (remove LCD cover AL skin)  Step 34. Divide Log UP assy (remove Log up AL skin)

Step 35. Divide Display Assy (Remove Touch Panel)  Step 36. Divide Log UP TP Assy (Remove TP Brk)